

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Please cancel claims 8-19 without waiver or prejudice.

1. (Original) An apparatus, comprising:

a first end of a via disposed in a semiconductor support layer, the first end having a first diameter; and

a second end of the via having a second diameter, the first diameter greater than the second diameter.
2. (Original) The apparatus of claim 1 wherein the via includes a shaft between the first end and the second end, the shaft having a shaft diameter similar to the second diameter.
3. (Original) The apparatus of claim 1 wherein the first end forms a semi-cone in the semiconductor support layer.
4. (Original) The apparatus of claim 1, further comprising a dielectric layer disposed proximate to the semiconductor support layer, the via to pass through the dielectric layer.
5. (Original) The apparatus of claim 4 wherein a diameter of the via in the dielectric layer is similar to the first diameter.

6. (Original) The apparatus of claim 4, further comprising a contact disposed on the dielectric layer and electrically coupled to the via.

7. (Original) The apparatus of claim 1 wherein the via includes a metal-filled via.

Claims 8-19 (canceled)

20. (Original) A die package, comprising:

a semiconductor support layer including a via having a first end and a second end in the semiconductor support layer, wherein a diameter of the first end is greater than a diameter of the second end;

a dielectric layer disposed proximate to the semiconductor support layer wherein the via passes through the dielectric layer; and

a contact disposed on the dielectric layer, the via coupled to the contact.

21. (Original) The die package of claim 20 wherein the via includes a shaft between the first end and the second end, a diameter of the shaft similar to the diameter of the second end.

22. (Original) The die package of claim 20 wherein the first end is a semi-cone shape centered on the via.

23. (Original) The die package of claim 22 wherein a diameter of the via through the dielectric layer is similar to a diameter of the semi-cone shape.
24. (Original) A system, comprising:
a printed circuit board (PCB); and
a processor coupled to the PCB, wherein the processor includes:
a semiconductor support layer including a via having a first end and a second end in the semiconductor support layer, wherein the first end having a first diameter and the second end having a second diameter, the first diameter greater than the second diameter;
a dielectric layer disposed proximate to the semiconductor support layer wherein the via passes through the dielectric layer; and
a contact disposed on the dielectric layer, the via coupled to the contact.
25. (Original) The system of claim 24 wherein the via includes a shaft between the first end and the second end, the shaft having a shaft diameter similar to the second diameter.
26. (Original) The system of claim 25 wherein the first end tapers outward from a center of the via within the semiconductor support layer towards the dielectric layer, the first end defining a semi-cone shape in the semiconductor support layer.
27. (Original) The system of claim 24 wherein the first diameter is approximately twice the second diameter.